

09/806401

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Harry Hedler, Gregor Feiertag,  
Peter Deml, and Franz Petter

Filed: PCT/DE99/03247 October 8, 1999

For: ELECTRONIC MODULE, ESPECIALLY A  
MULTICHIP MODULE, WITH MULTI-LAYER  
METALLIZATION AND CORRESPONDING  
PRODUCTION METHOD

Commissioner for Patents and Trademarks  
Washington DC 20231

Dear Sir:

**PRELIMINARY AMENDMENT**

In the above-mentioned PCT application, please accept the enclosed application under the national stage pursuant to 35 USC § 371 and amend the application as follows:

**In the Claims:**

Please replace claims 1-8 of the application with claims 1-9 as follows:

41  
1. An electronic module, in particular a multichip module, comprising a multilayer wiring having at least one IC component applied on the component side thereof, said module being unilaterally covered on the component side with a hermetic case, and comprising contact pads on the bottom side of the module through for contacting and integration of the module to a next higher assembly group level, the bottom side of the multilayer wiring constituting directly, without additional wiring substrate, the bottom side of the module, the component side of the multilayer wiring adhering to the hermetic case with